

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5427345	gold au	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 11:46
L2	19777	(interposer interposing interposed interpose) with (elastomeric elastic compliant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 11:46
L3	15	1 with 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 11:23
L4	32024	(interposer interposing interposed interpose) same (elastomeric elastic compliant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 11:46
L5	413	4 same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 11:46
L6	1466920	(semiconductor die chip electronic component ic (integrated adj circuit)) same (((wiring printed circuit) adj4 board) carrier substrate board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 11:47
L7	104	5 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 11:47

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1466920	(semiconductor die chip electronic component ic (integrated adj circuit)) same (((wiring printed circuit) adj4 board) carrier substrate board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 08:46
L2	32799	(interposer interposing interposed) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 08:47
L3	19777	(interposer interposing interposed interpose) with (elastomeric elastic compliant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 08:48
L4	723	1 same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 08:48